

# MB05F~MB10F

## Miniature Glass Passivated Single-Phase Surface Mount Flat Bridge Rectifier

### Major Ratings and Characteristics

$I_{F(AV)}$	0.5A , 0.8A
$V_{RRM}$	50-1000V
$I_{FSM}$	35 A
$I_R$	5.0 $\mu$ A
$V_F$	1.0V
$T_j$ max.	150 °C

### Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering: 260 °C/10 seconds at terminals
- Component in accordance to RoHS 2002/95/1 and WEEE 2002/96/EC

### Mechanical Data

- Case: MBF Molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Polarity symbols marked on body

### Maximum Ratings & Thermal Characteristics & Electrical Characteristics

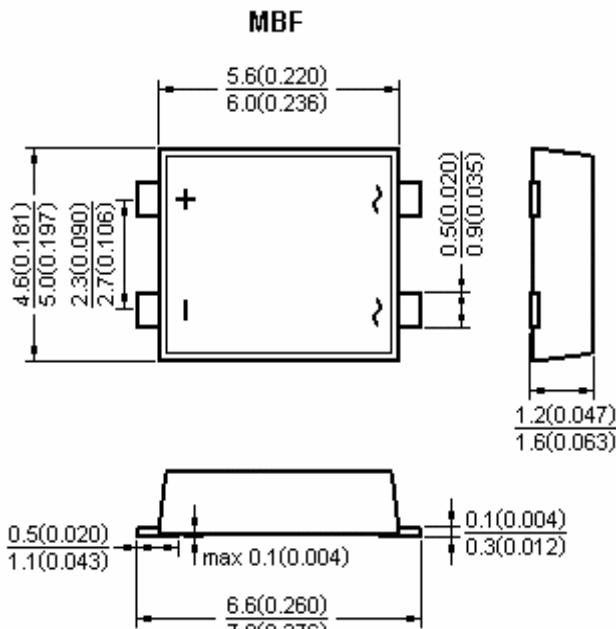
( $T_A = 25$  °C unless otherwise noted)

	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward output rectified current at $T_A=30$ °C -on glass-epoxy P.C.B.(NOTE 1) -on aluminum substrate(NOTE 2)	$I_{F(AV)}$				0.5				A
					0.8				
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load(JEDEC Method)	$I_{FSM}$				35				A
Maximum instantaneous forward voltage drop per leg at 0.4A	$V_F$				1.0				V
Maximum DC reverse current at $T_A = 25$ °C rated DC blocking voltage per leg $T_A = 125$ °C	$I_R$				5.0				$\mu$ A
					100				
Typical junction capacitance per leg at 4.0 V ,1MHz (NOTE 1)	$C_J$				13				p F
Thermal resistance per leg (NOTE 2)	$R_{\theta JA}$				85				°C/W
(NOTE 1)	$R_{\theta JL}$				70				
(NOTE 1)	$R_{\theta JL}$				20				
Operating junction and storage temperature range	$T_j, T_{STG}$				-55 to +150				°C

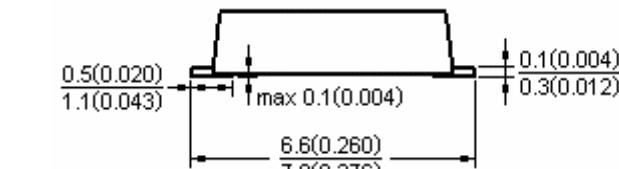
NOTE1:On glass epoxy P.C.B. mounted on 0.05×0.05" (1.3×1.3mm) pads

NOTE2:On aluminum substrate P.C.B. with an area of 0.8×0.8" (20×20mm) mounted on 0.05×0.05" (1.3×1.3mm) solder pad

Patent Pending



Dimensions in millimeters and (inches)



-	$R_{\theta JA}$	85							
(NOTE 2)	$R_{\theta JA}$	70							
(NOTE 1)	$R_{\theta JL}$	20							
Operating junction and storage temperature range	$T_j, T_{STG}$	-55 to +150							

Characteristic Curves ( $T_A=25^\circ\text{C}$  unless otherwise noted)